

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

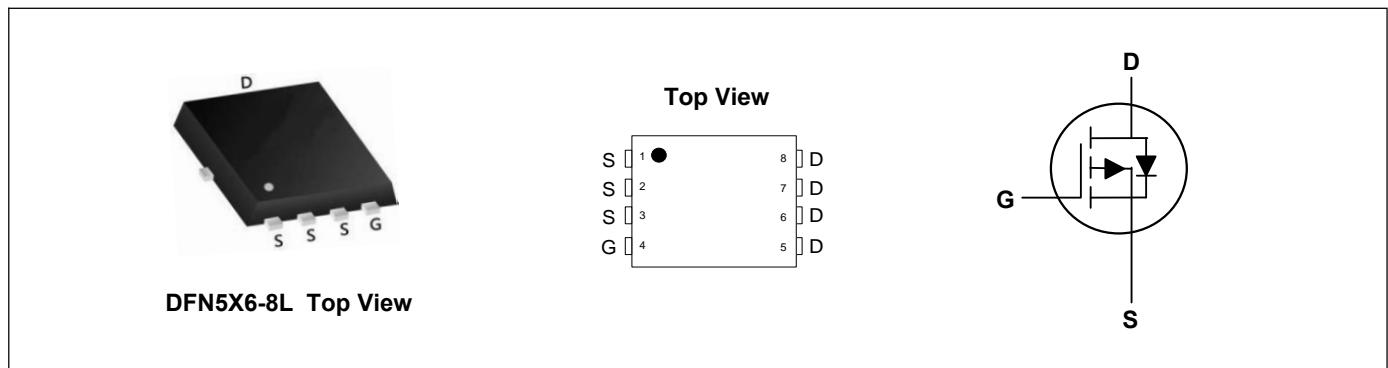
Product Summary



V_{DS}	-100	V
I_D	-30	A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	90	mΩ
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	105	mΩ

Applications

- High Frequency Point-of-Load,Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



Absolute Maximum Ratings($T_c=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ -10V^1$	$I_D @ T_c = 25^\circ C$	-30	A
Continuous Drain Current, $V_{GS} @ -10V^1$	$I_D @ T_c = 100^\circ C$	-15	A
Pulsed Drain Current ²	I_{DM}	-75	A
Single Pulse Avalanche Energy ³	EAS	157.2	mJ
Avalanche Current	I_{AS}	18.9	A
Total Power Dissipation ⁴	$P_D @ T_c = 25^\circ C$	50	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	50	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	2.5	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-100	---	---	V
Static Drain-Source On-Resistance ²	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}$, $I_D=-10\text{A}$	---	70	90	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_D=-8\text{A}$	---	80	105	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = -250\mu\text{A}$	-1.2	-1.6	-2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=-100\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-50	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{\text{DS}}=-10\text{V}$, $I_D=-10\text{A}$	---	24	---	S
Total Gate Charge	Q_g	$V_{\text{DS}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_D=20\text{A}$	---	48.5	---	nC
Gate-Source Charge	Q_{gs}		---	9.13	---	
Gate-Drain Charge	Q_{gd}		---	5.93	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_G=3.3\Omega$, $I_D=10\text{A}$	---	12	---	ns
Rise Time	T_r		---	27.4	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	79	---	
Fall Time	T_f		---	53.6	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	3689	---	pF
Output Capacitance	C_{oss}		---	129	---	
Reverse Transfer Capacitance	C_{rss}		---	76	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ^{1,5}	I_S	$V_G=V_D=0\text{V}$, Force Current	---	---	-30	A
Diode Forward Voltage ²	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_S=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V
Reverse Recovery Time	t_{rr}	$I_F=-8\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	38.7	---	nS
Reverse Recovery Charge	Q_{rr}		---	22.4	---	nC

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=-25\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.88\text{mH}$, $I_{\text{AS}}=-18.9\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

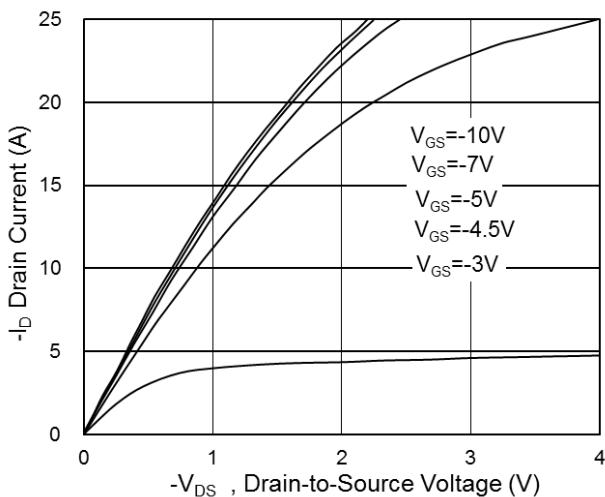


Fig.1 Typical Output Characteristics

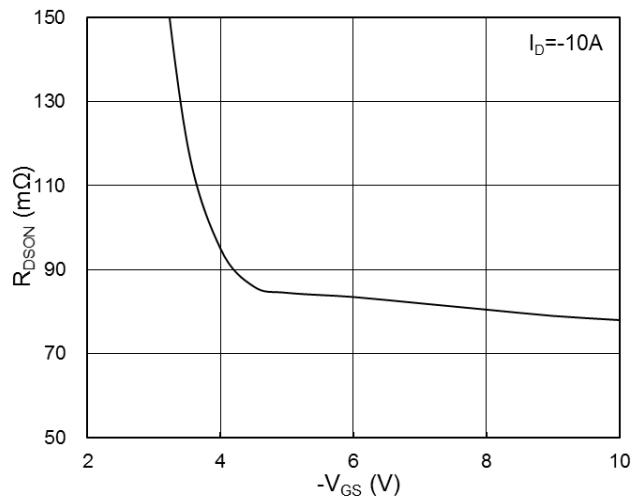


Fig.2 On-Resistance vs G-S Voltage

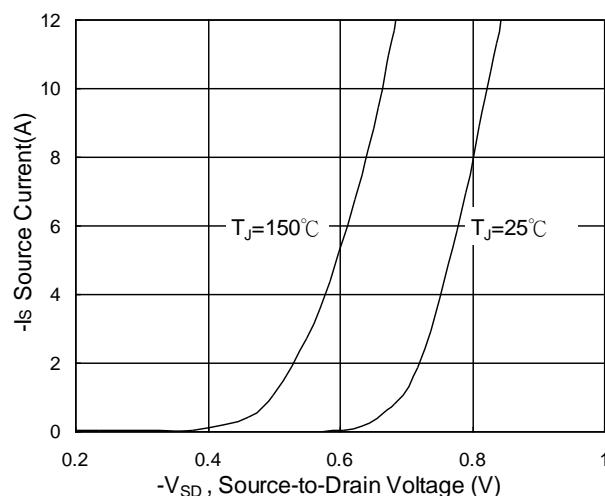


Fig.3 Typical S-D Diode Forward Voltage

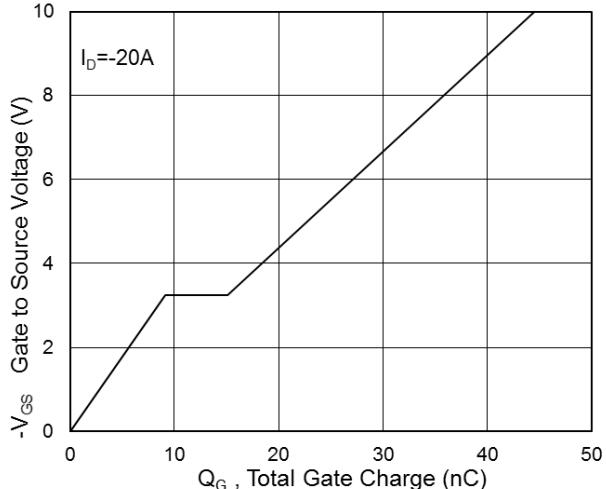


Fig.4 Gate-Charge Characteristics

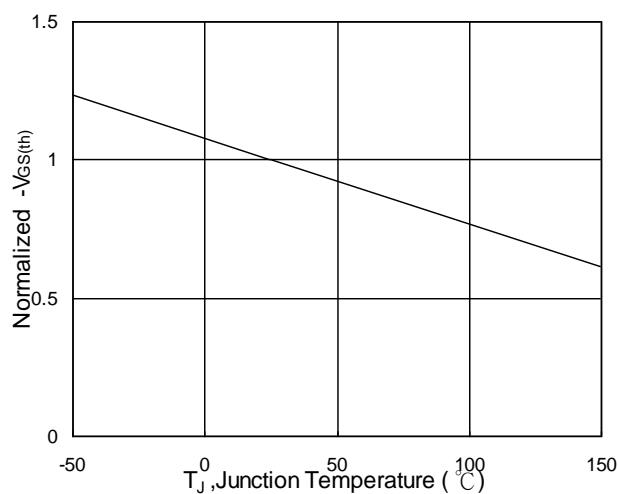


Fig.5 Normalized $V_{GS(th)}$ vs T_J

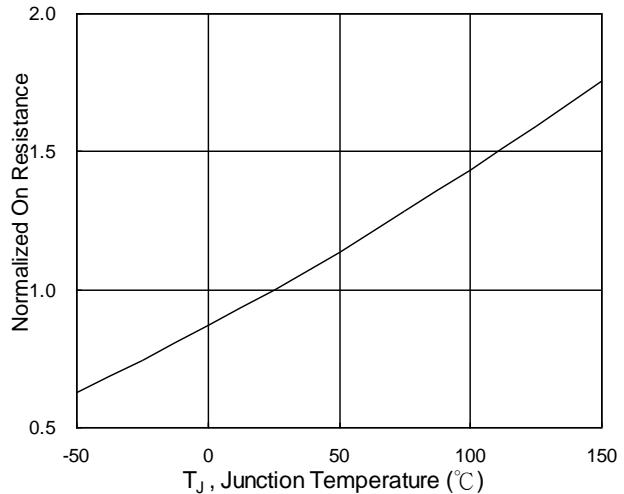
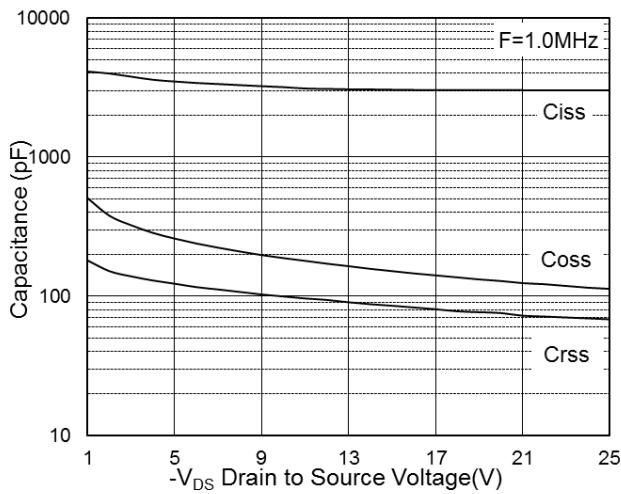
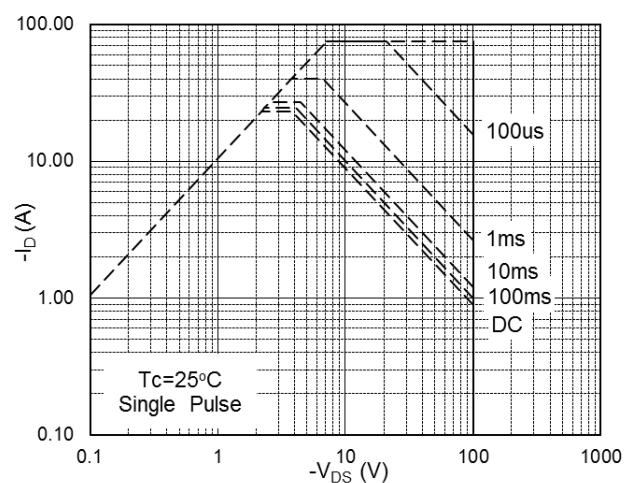
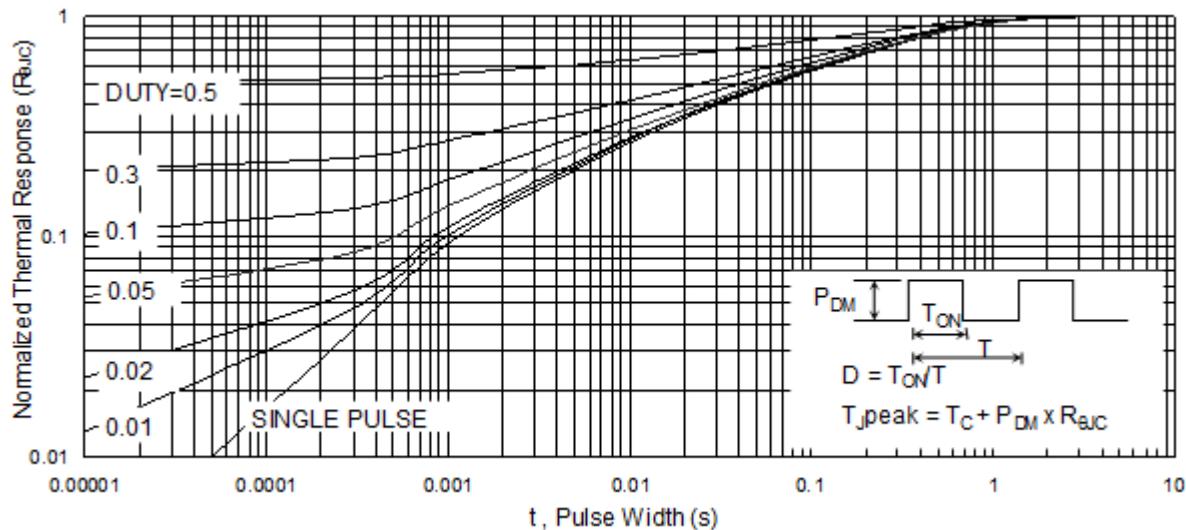
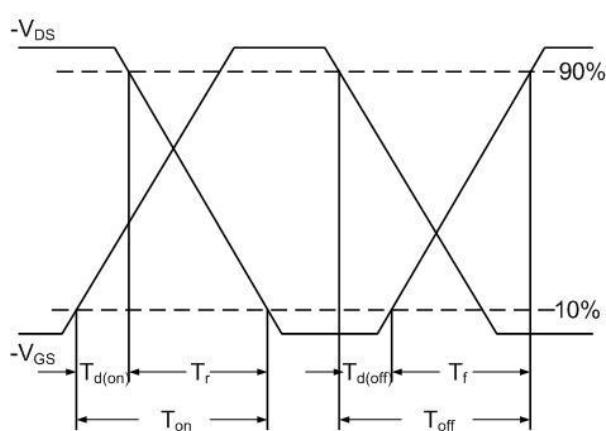
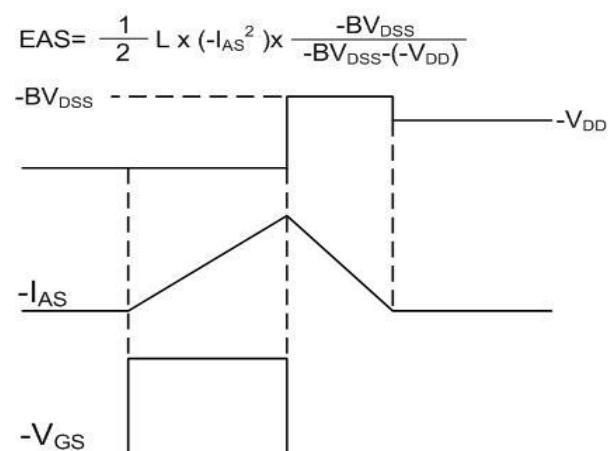
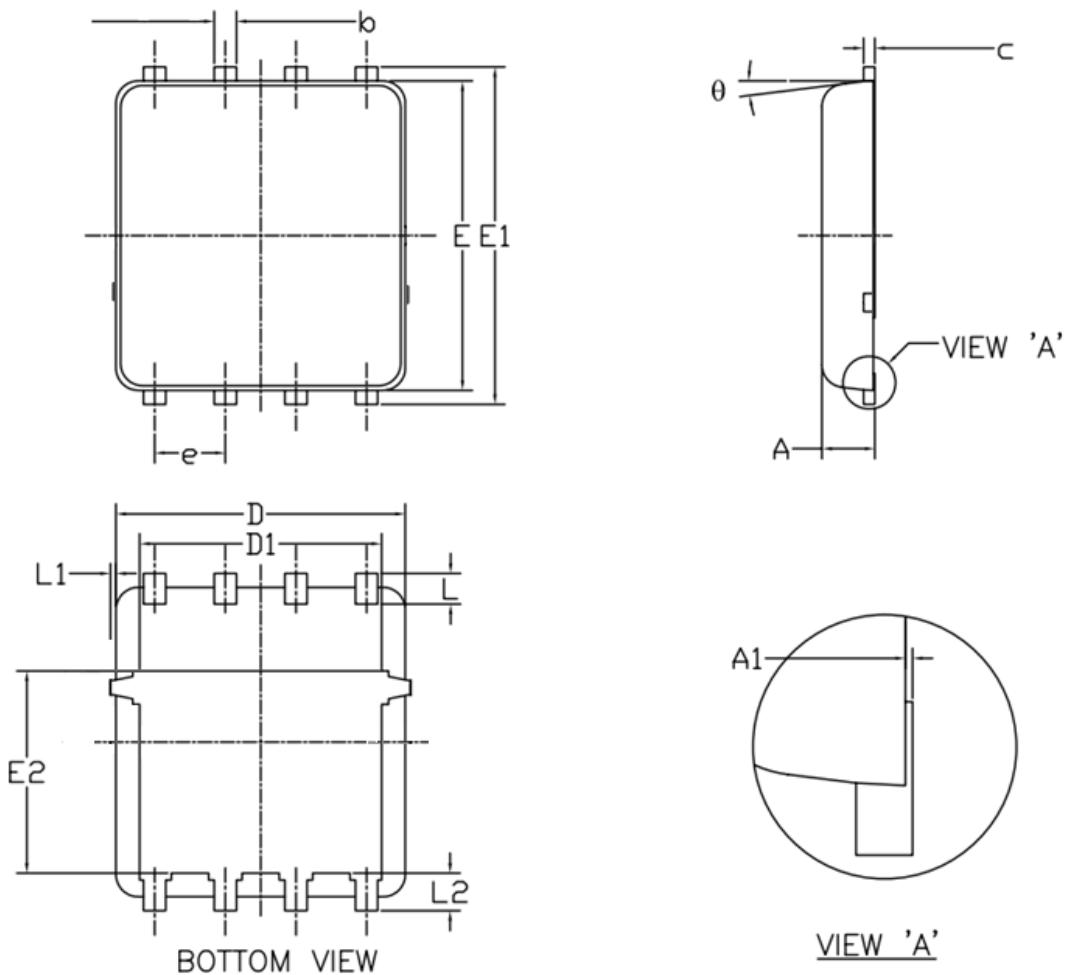


Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform

DFN5X6-8L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.00	1.20	E1	5.90	6.10	6.35
A1	0.00	--	0.05	E2	3.38	3.58	3.92
b	0.30	0.40	0.51	e	1.27 BSC		
c	0.20	0.25	0.33	L	0.51	0.61	0.71
D	4.80	4.90	5.40	L1	--	--	0.15
D1	3.61	4.00	4.25	L2	0.41	0.51	0.61
E	5.65	5.80	6.06	θ	0°	--	12°